

Specification of Thermoelectric Module

TETS1-07139

Description

The 71 couples, 23mm x 23mm size module is a single stage module which is made of our high performance ingot to achieve superior cooling performance and 70°C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

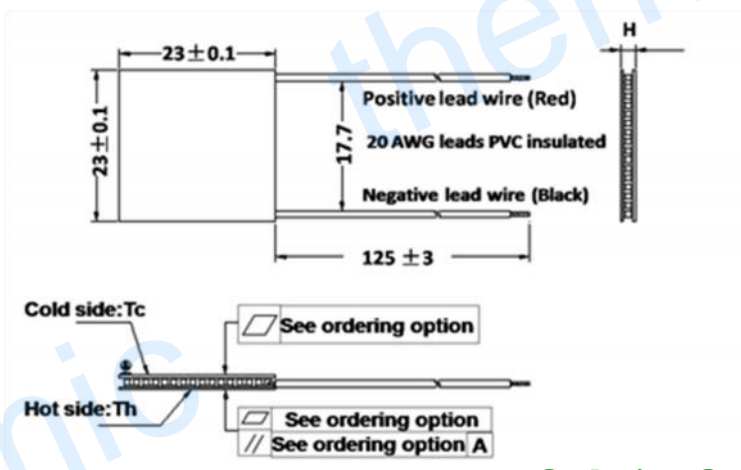
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

| | | | |
|----------------------------|------|------|---|
| Th (°C) | 27 | 50 | Hot side temperature at environment: dry air, N ₂ |
| DT _{max} (°C) | 70 | 79 | Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side |
| U _{max} (Voltage) | 9.0 | 9.4 | Voltage applied to the module at DT _{max} |
| I _{max} (Amps) | 4.1 | 4.1 | DC current through the modules at DT _{max} |
| Q _{Cmax} (Watts) | 23.0 | 24.8 | Cooling capacity at cold side of the module under DT=0 °C |
| AC resistance (Ohms) | 1.67 | 1.8 | The module resistance is tested under AC |
| Tolerance (%) | ± 10 | | For thermal and electricity parameters |

Geometric Characteristics Dimensions in millimeters



Manufacturing Options

A. Solder:

1. T100: BiSn (T_{melt}=138°C)
2. T200: CuAgSn (T_{melt} = 217°C)
3. T240: SbSn (T_{melt} = 240°C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

Ordering Option

| Suffix | Thickness H (mm) | Flatness/ Parallelism (mm) | Lead wire length(mm) Standard/Optional length |
|--------|------------------|----------------------------|--|
| TF | 0:3.4± 0.1 | 0: 0.07/0.07 | 125±3/Specify |
| TF | 1:3.4 ± 0.03 | 1: 0.025/0.025 | 125±3/Specify |

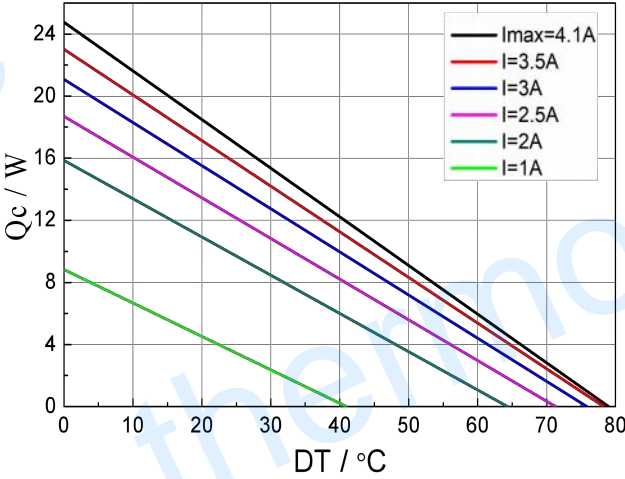
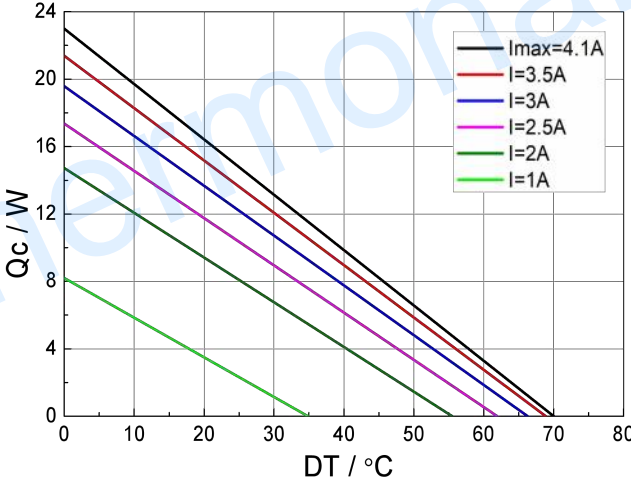
Eg. TF01: Thickness 3.4± 0.1 (mm) and Flatness 0.025/0.025 (mm)

Operation Cautions

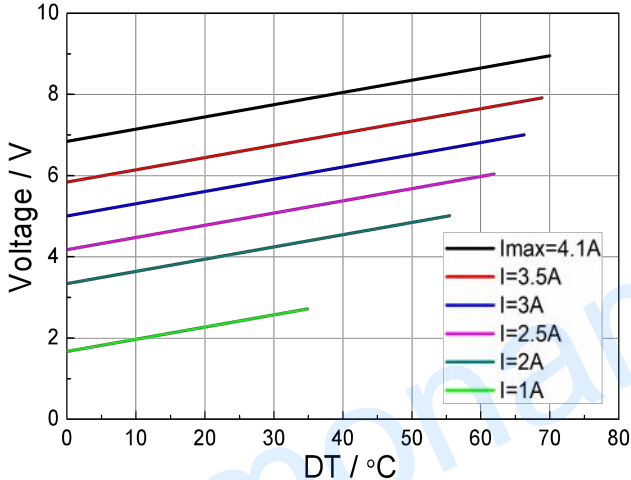
- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Work under DC

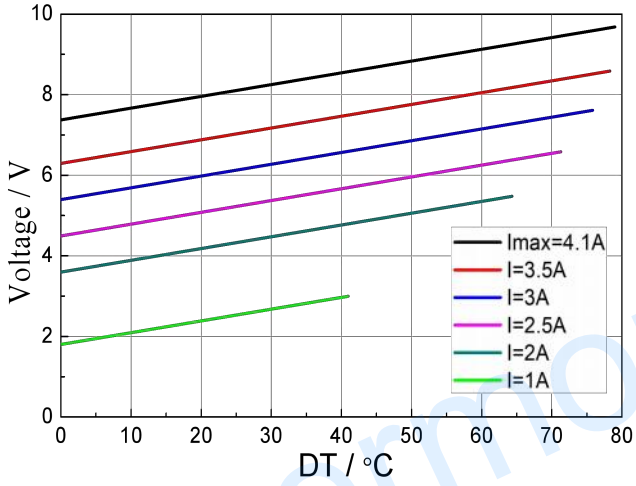
Performance Curves at $T_h=27\text{ }^\circ\text{C}$

Performance Curves at $T_h=50\text{ }^\circ\text{C}$

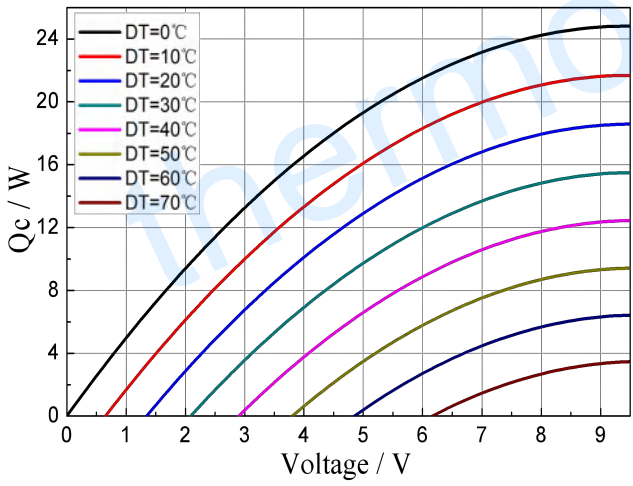
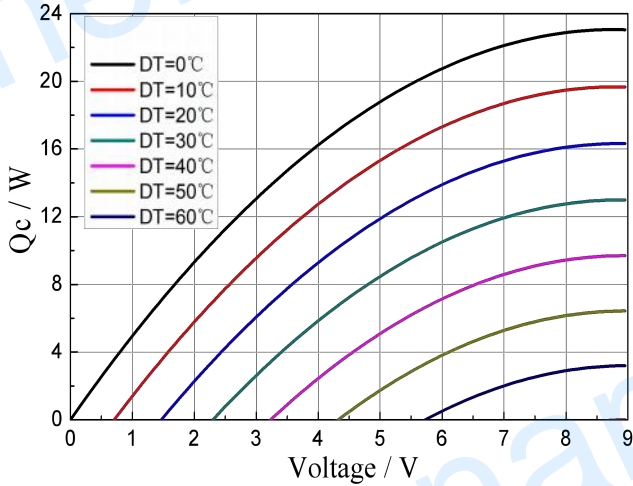


Standard Performance Graph $Q_c = f(DT)$





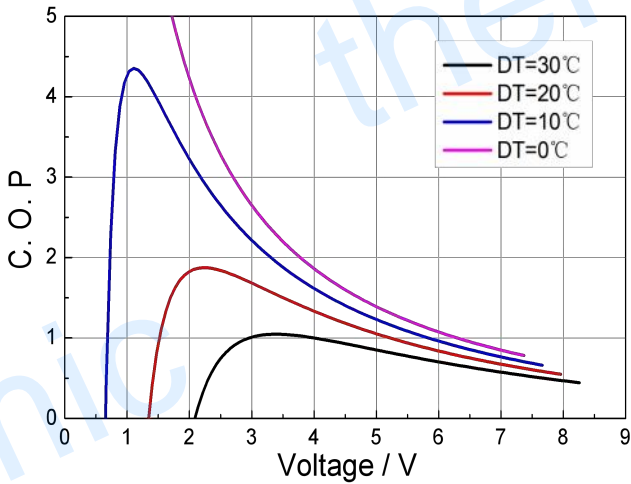
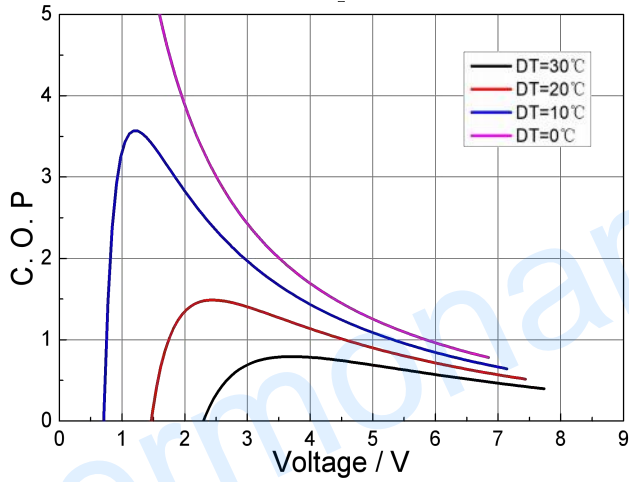
Standard Performance Graph $V= f(DT)$



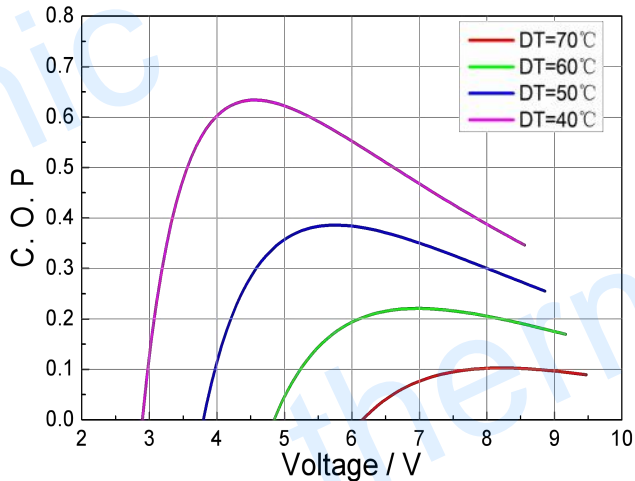
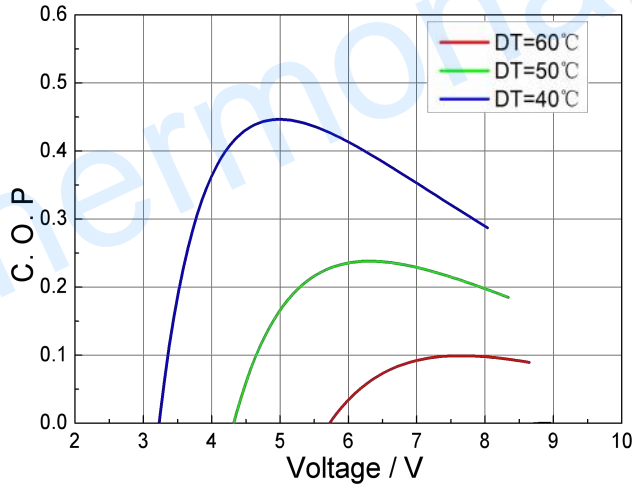
Standard Performance Graph $Q_c= f(V)$

Performance Curves at $T_h=27^\circ C$

Performance Curves at $T_h=50^\circ C$



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



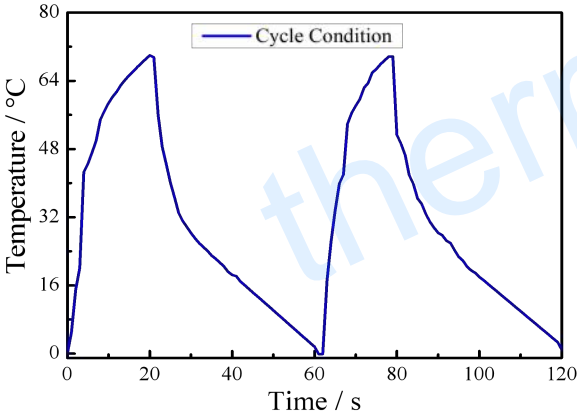
Standard Performance Graph COP = f(V) of DT ranged from 40 to 70 °C

60/70 °C

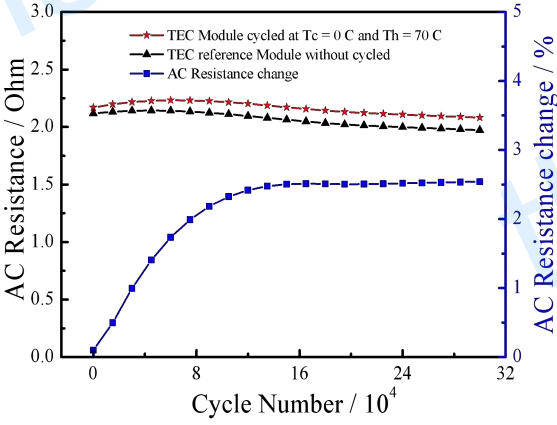
Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

A typical 127 couples module is fabricated by the unique “soft” process and has demonstrated that it only has 2.5% degrading after 300,000 thermal cycling. The below graphic shows that in beginning 120,000 cycles, it degrade about 2.5%, and then go on stable with very tiny degrading in further 180,000 thermal cycles. It is derived out that the modules can go over million thermal cycles.

TEC Thermal Cycle Lifetime Test On TETC1-12706



Typical cooling-heating cycle



The Chart for AC Resistance and AC Resistance Changes
vs Cycle Number